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(12) **United States Design Patent**  
**Shi et al.**

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(54) **LIGHT-EMITTING DIODE PACKAGE**

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(\*\*) Term: **14 Years**

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(51) **LOC (10) Cl.** ..... **13-03**

(52) **U.S. Cl.**  
USPC ..... **D13/180**

(58) **Field of Classification Search**

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CPC ... H01L 25/167; H01L 25/0753; H01L 27/15;  
H01L 27/156; H01L 31/02; H01L 33/00;  
H01L 33/04; H01L 33/08; H01L 33/10;  
H01L 33/20; H01L 33/38; H01L 33/42;  
H01L 33/48; H01L 33/62; H01L 33/483;  
H01L 33/486; F21K 9/00; F21K 9/30; F21K  
9/54

See application file for complete search history.

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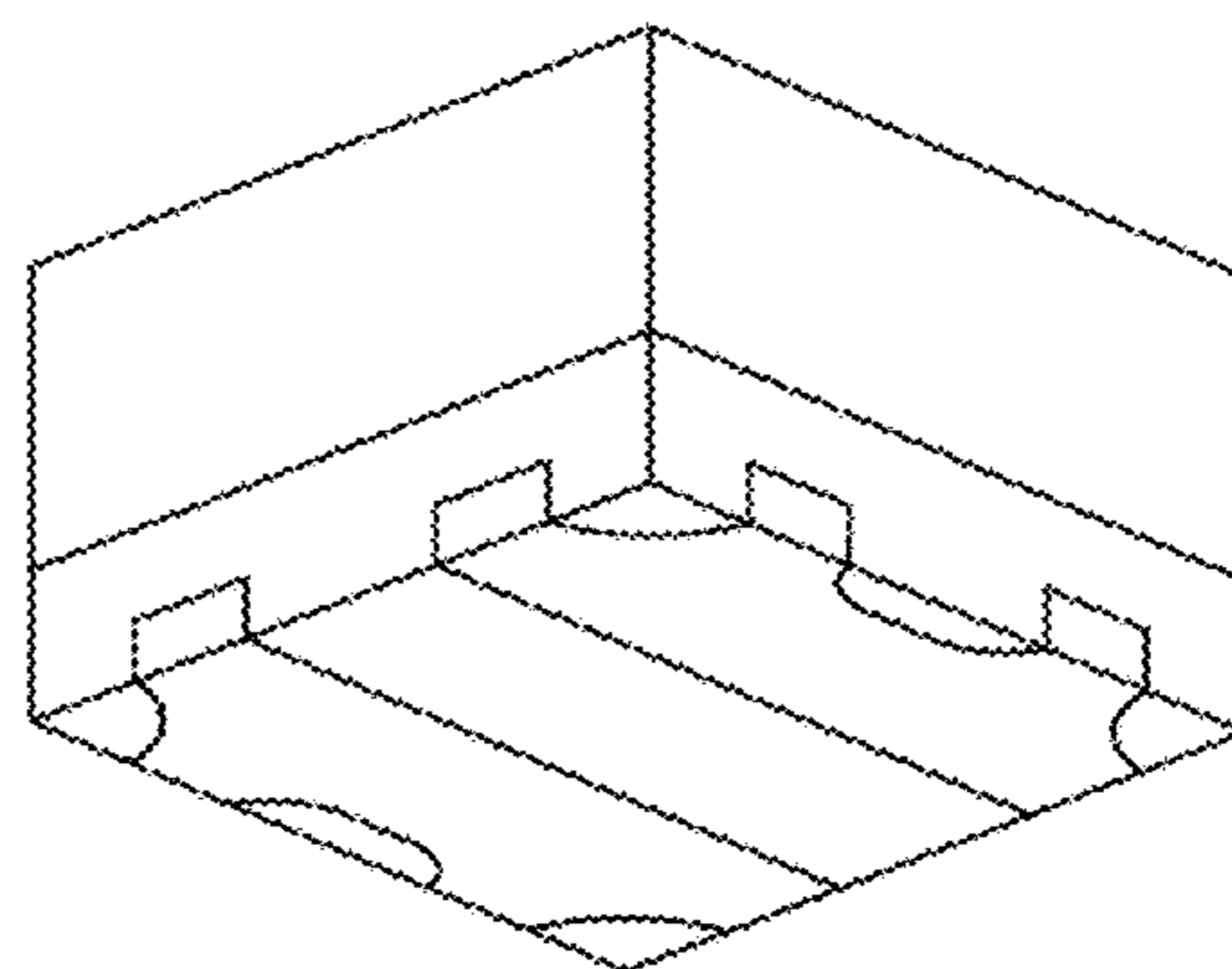
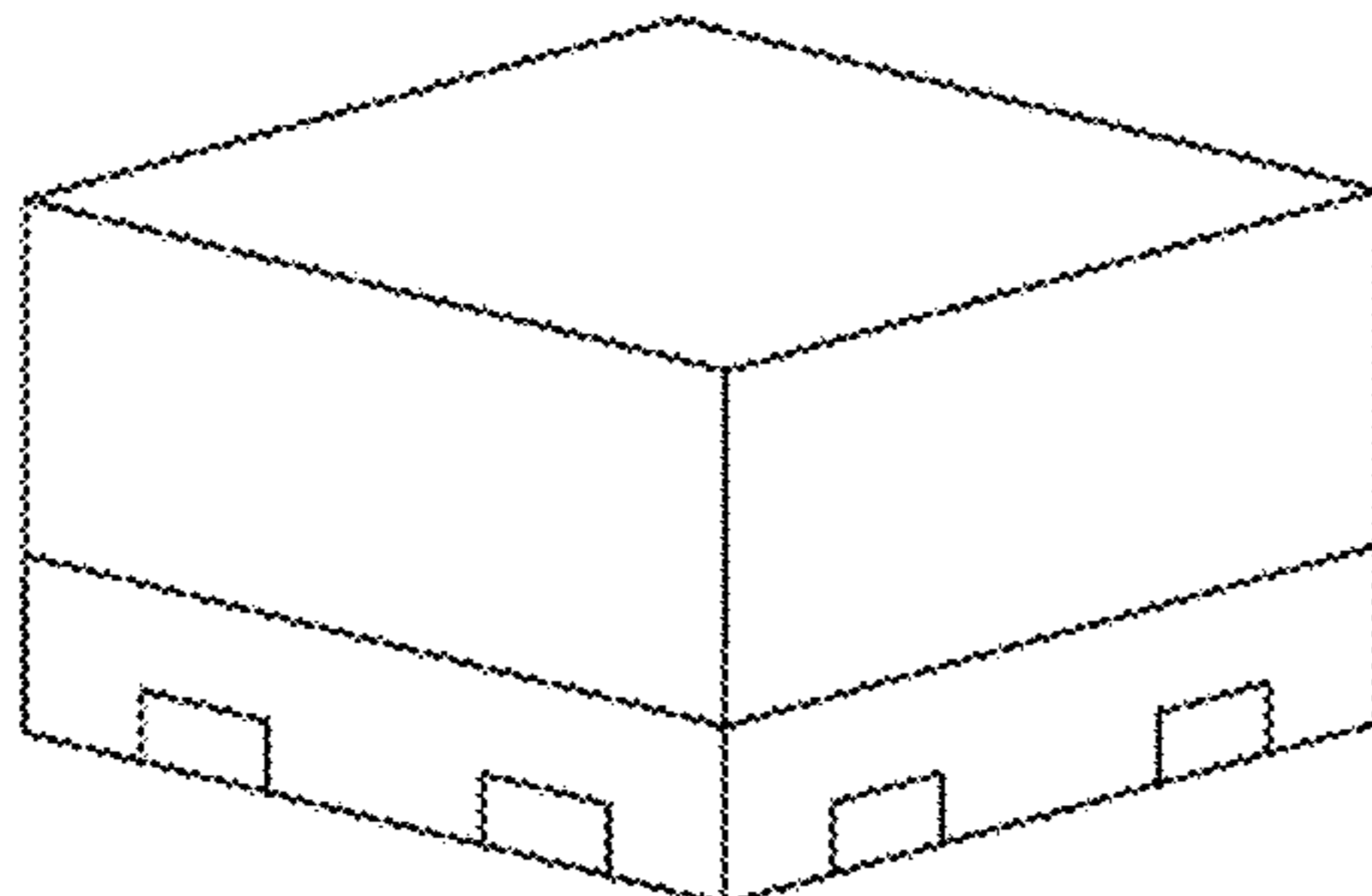
(57) **CLAIM**

The ornamental design for a light-emitting diode package, substantially as shown and described.

**DESCRIPTION**

FIG. 1 is a front view of a light emitting diode package according to a first embodiment of the disclosure; FIG. 2 is a rear view of a light emitting diode package according to the first embodiment of the disclosure; FIG. 3 is a left side view of a light emitting diode package according to the first embodiment of the disclosure; FIG. 4 is a right side view of a light emitting diode package according to the first embodiment of the disclosure; FIG. 5 is a top view of a light emitting diode package according to the first embodiment of the disclosure; FIG. 6 is a bottom view of a light emitting diode package according to the first embodiment of the disclosure; FIG. 7 is a perspective view of a light emitting diode package according to the first embodiment of the disclosure; FIG. 8 is another perspective view of a light emitting diode package according to the first embodiment of the disclosure; FIG. 9 is a front view of a light emitting diode package according to a second embodiment of the disclosure; FIG. 10 is a rear view of a light emitting diode package according to the second embodiment of the disclosure; FIG. 11 is a left side view of a light emitting diode package according to the second embodiment of the disclosure; FIG. 12 is a right side view of a light emitting diode package according to the second embodiment of the disclosure; FIG. 13 is a top view of a light emitting diode package according to the second embodiment of the disclosure; FIG. 14 is a bottom view of a light emitting diode package according to the second embodiment of the disclosure; FIG. 15 is a perspective view of a light emitting diode package according to the second embodiment of the disclosure; and, FIG. 16 is another perspective view of a light emitting diode package according to the second embodiment of the disclosure.

**1 Claim, 6 Drawing Sheets**



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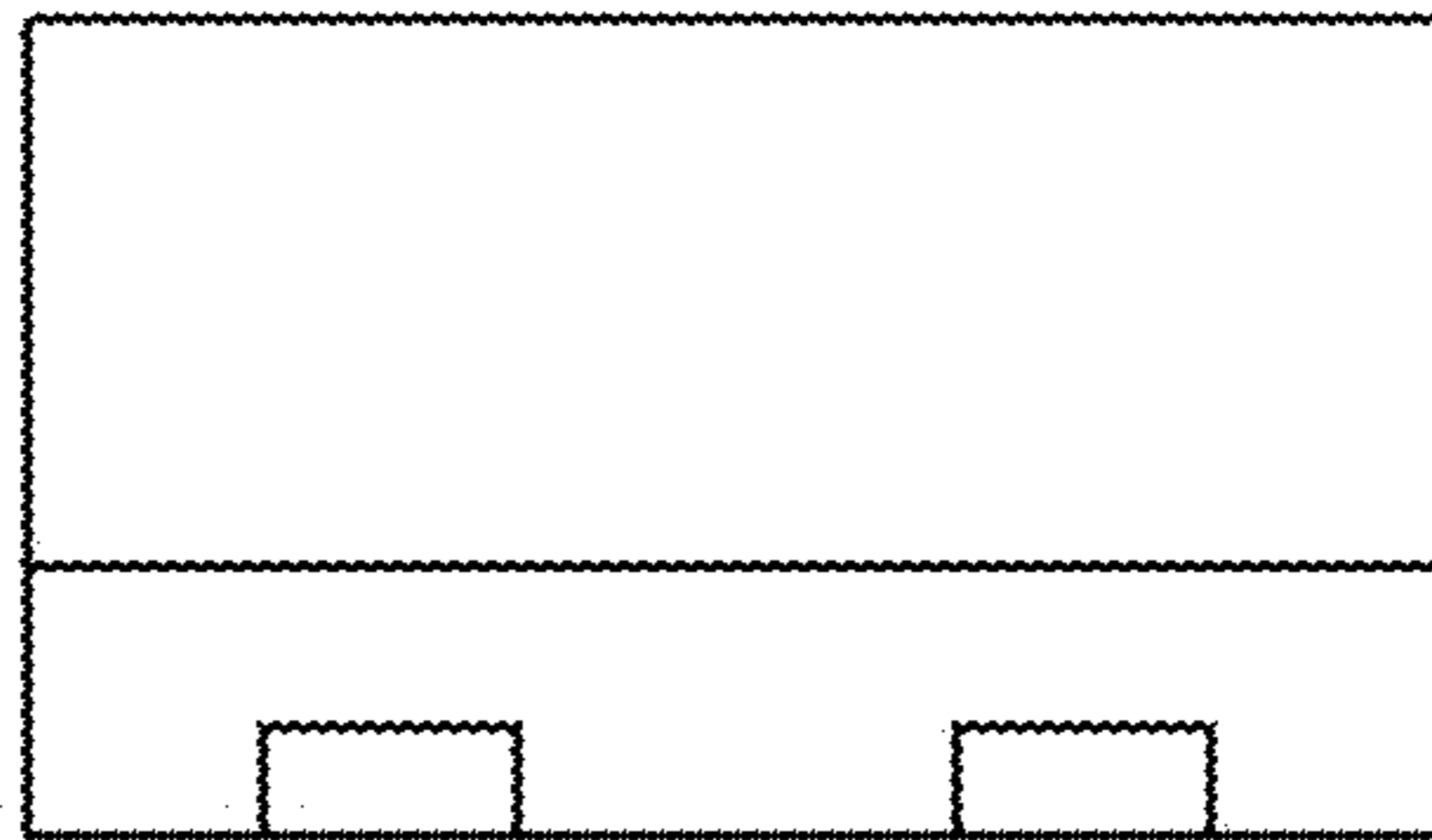


FIG. 1

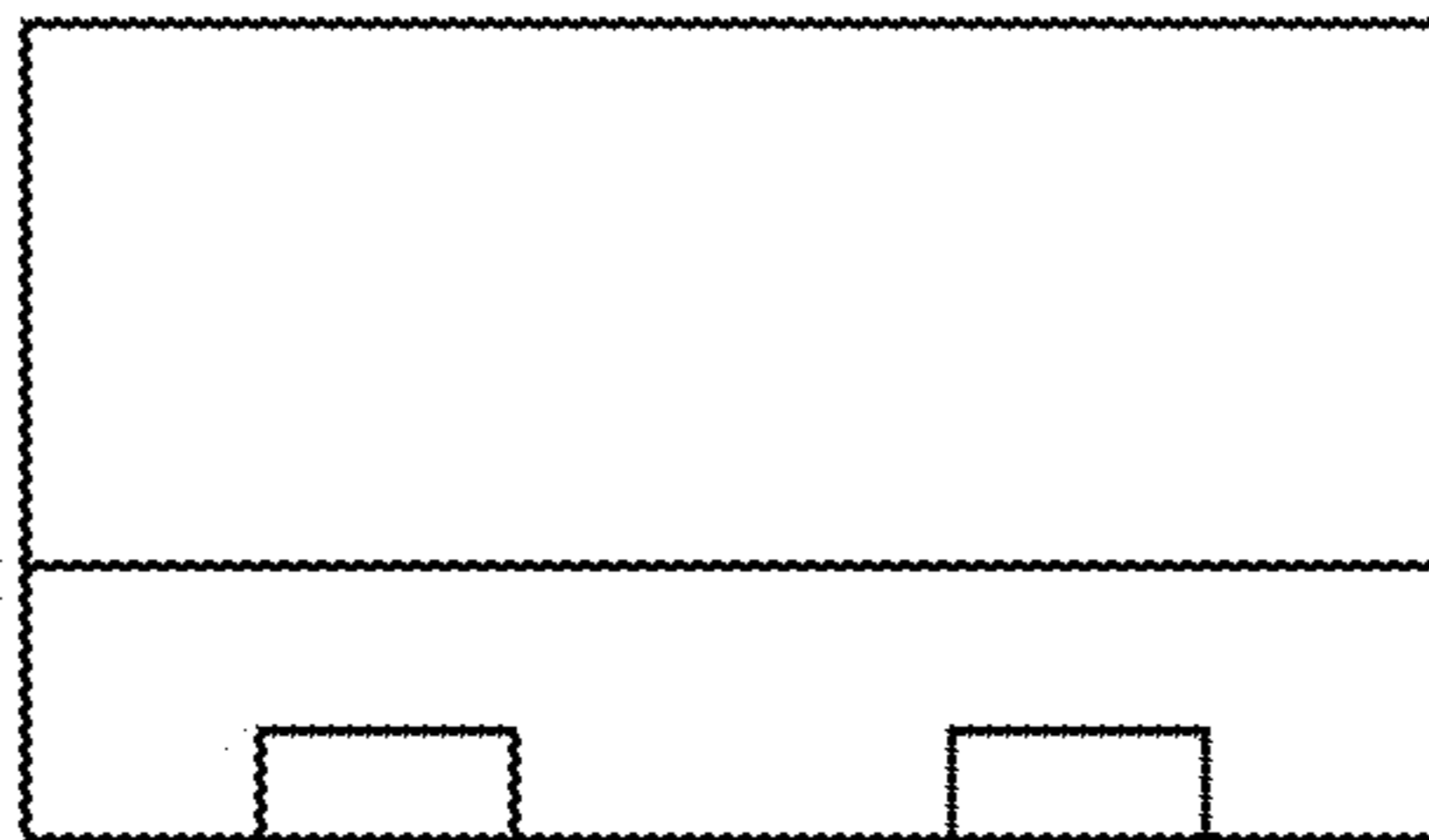


FIG. 2

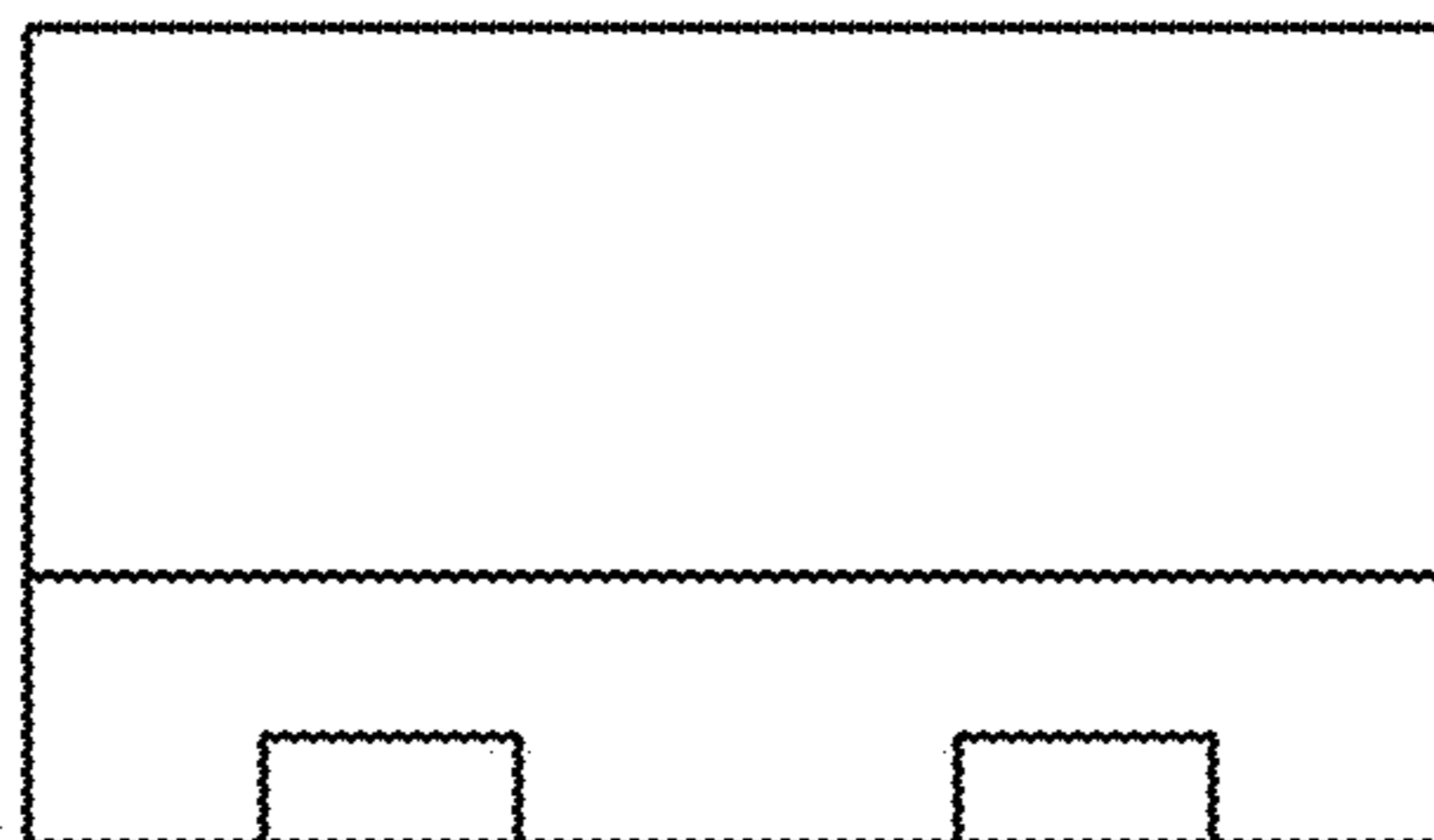


FIG. 3

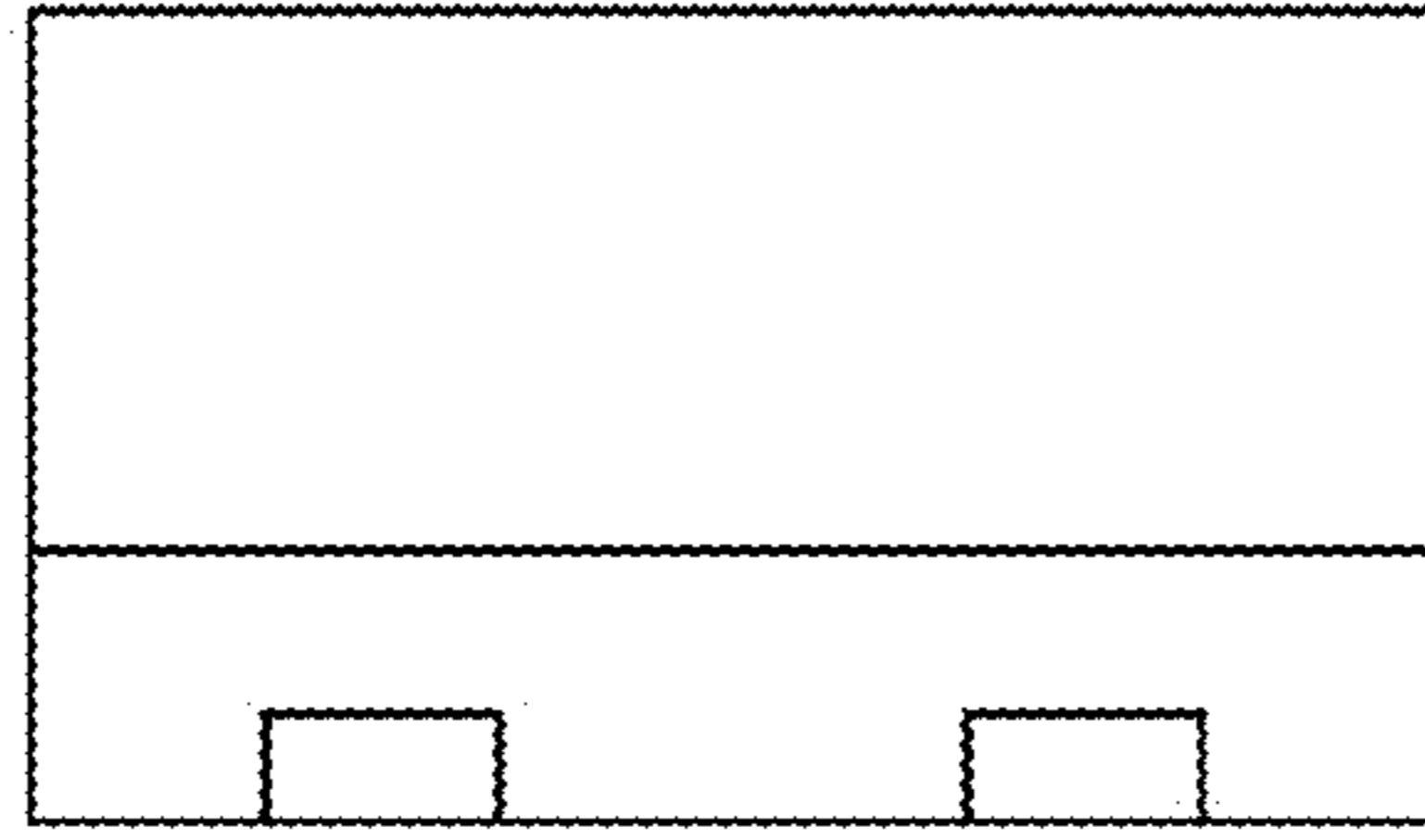


FIG. 4

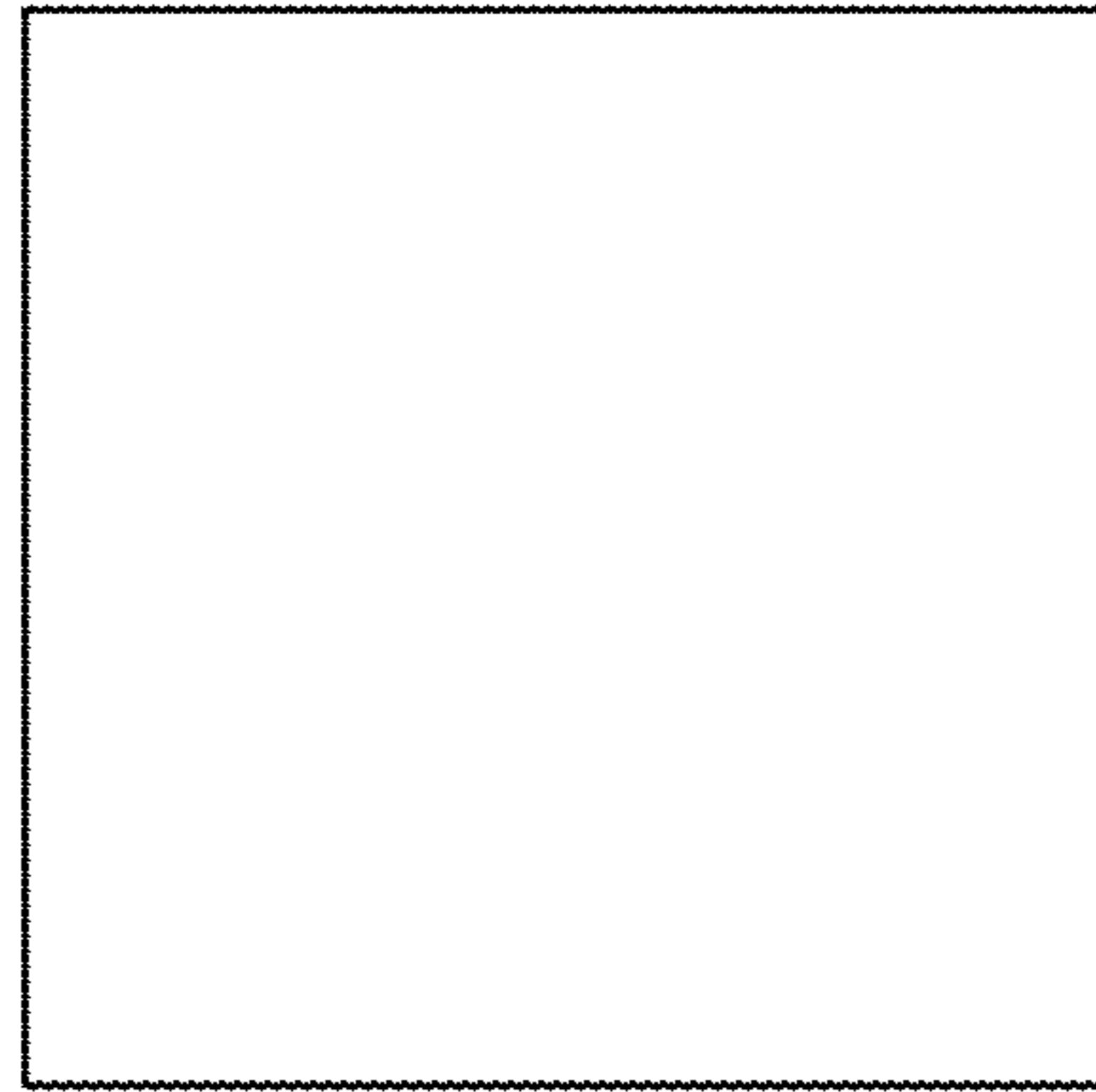


FIG. 5

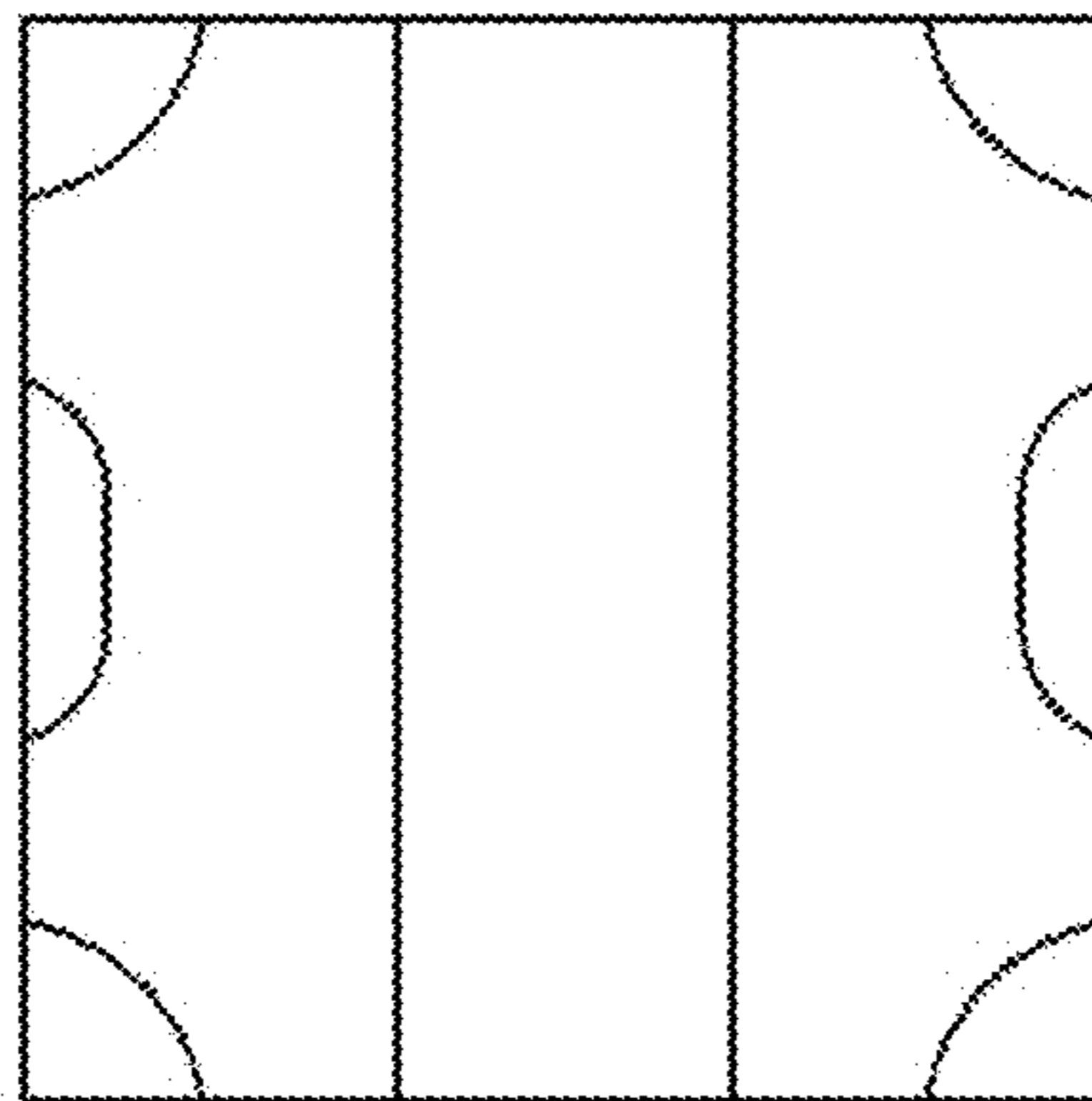


FIG. 6

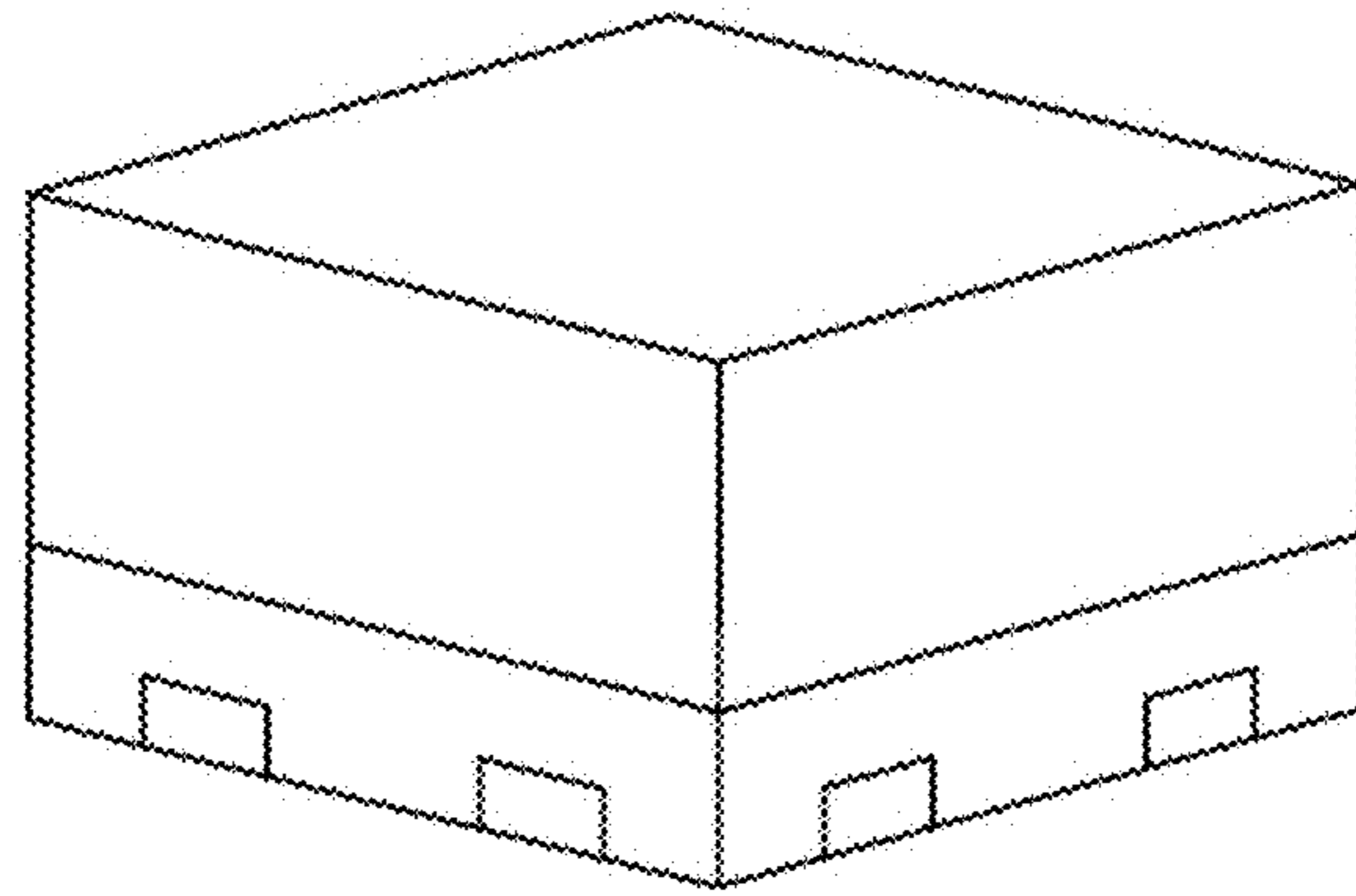


FIG. 7

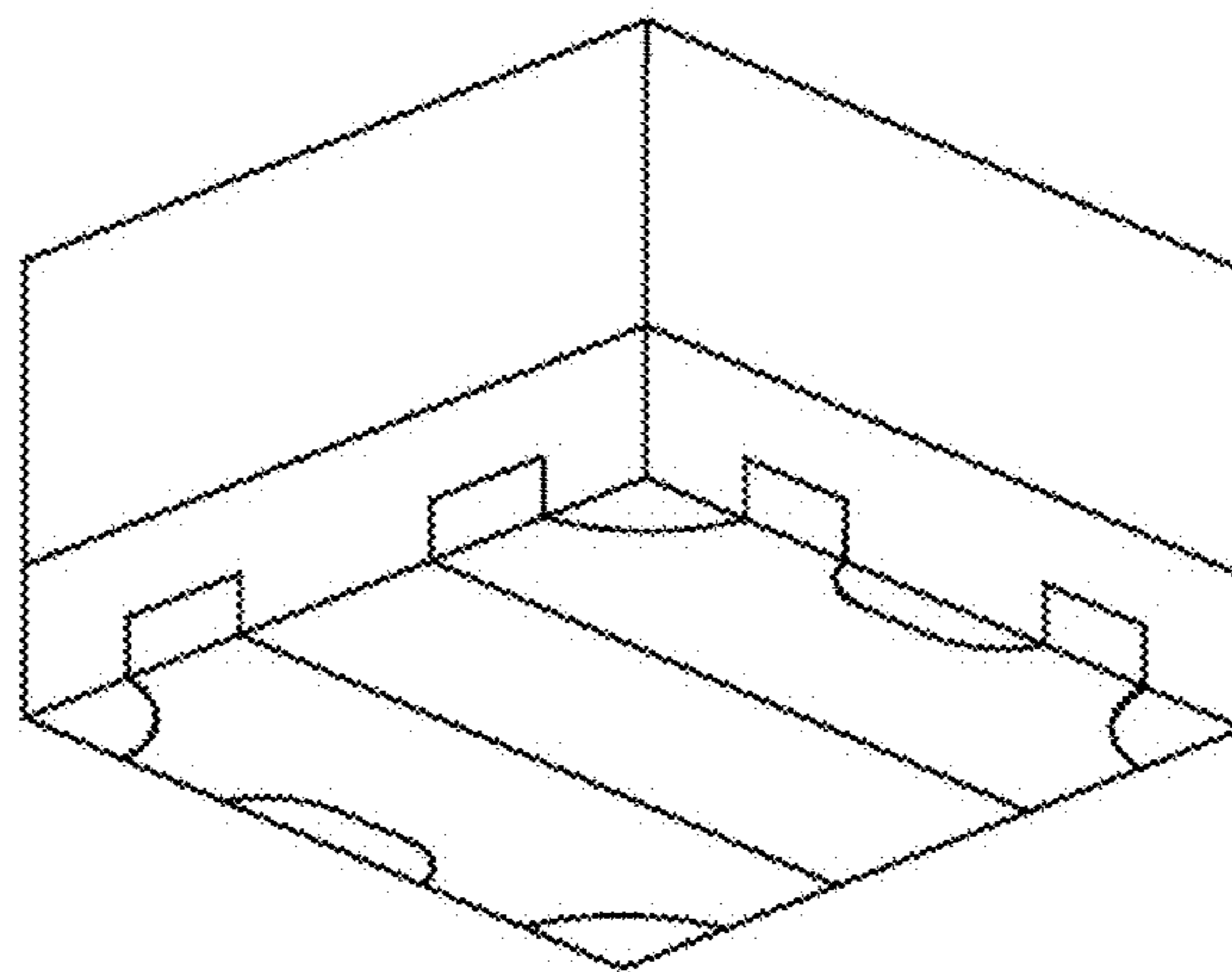


FIG. 8

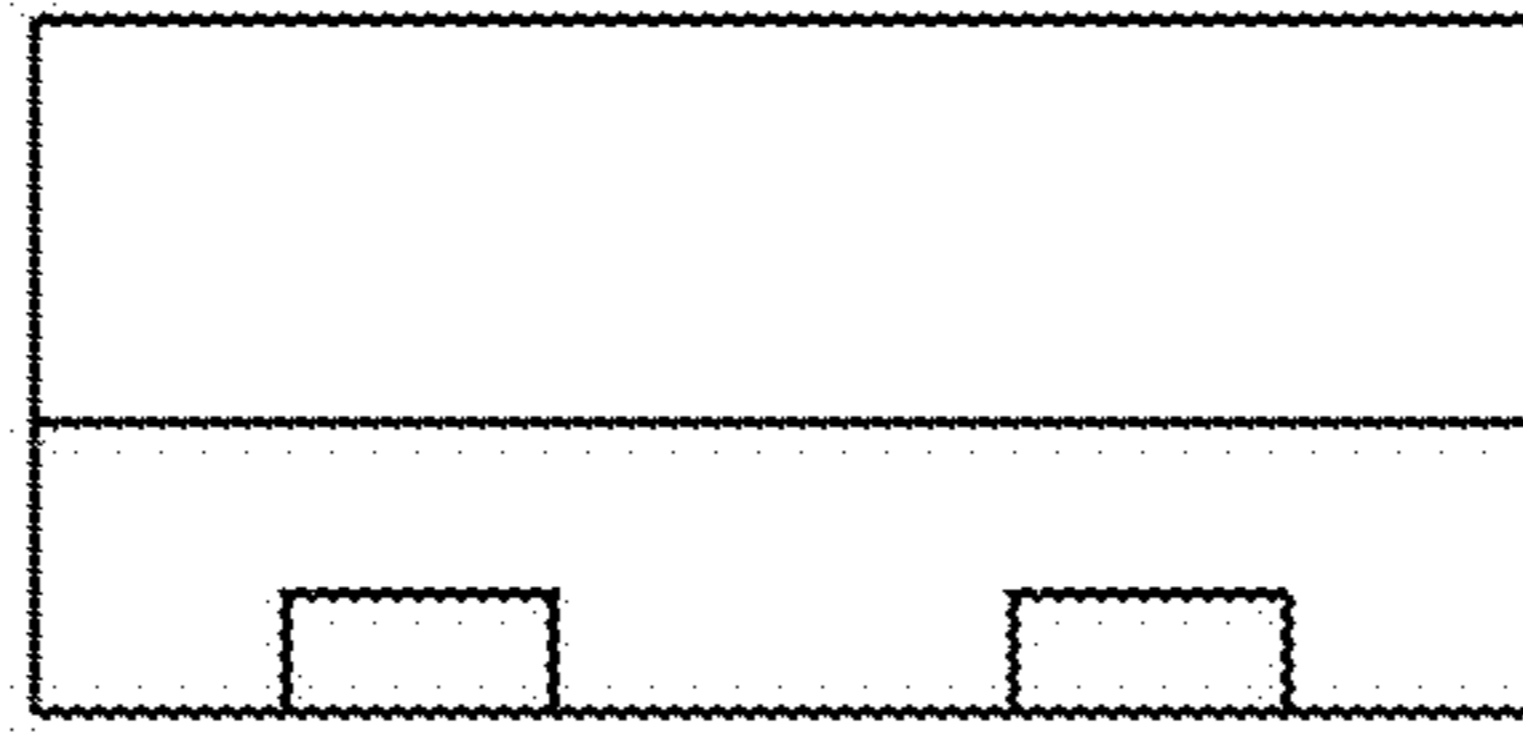


FIG. 9

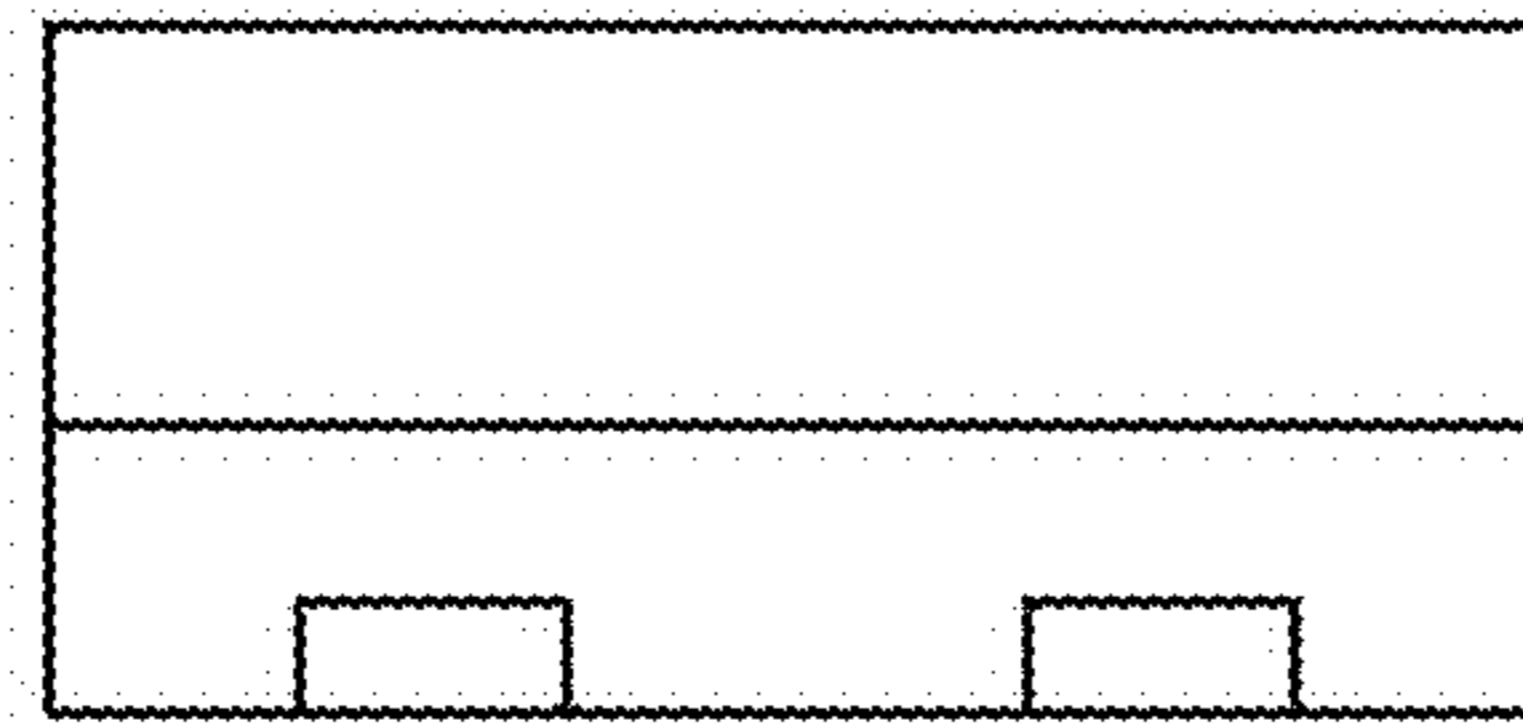


FIG. 10

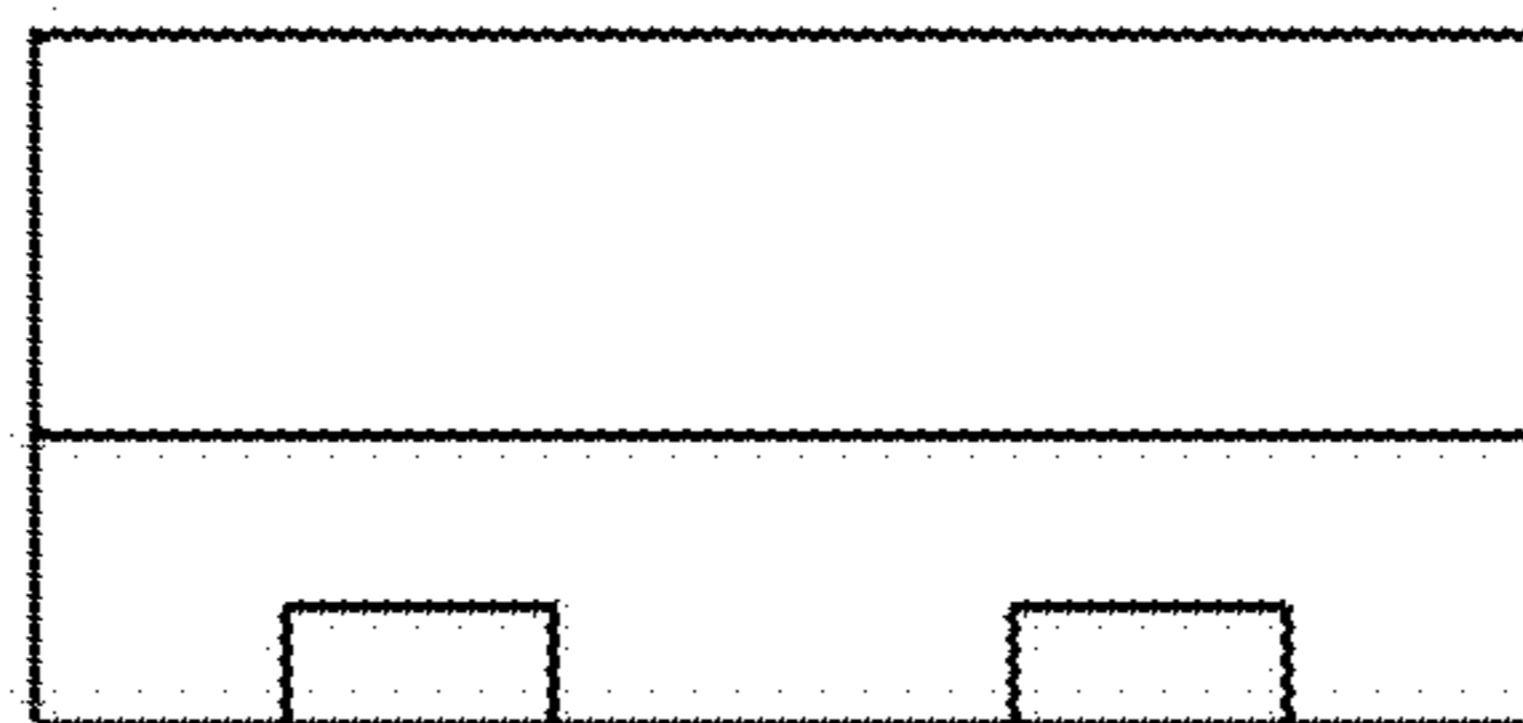


FIG. 11

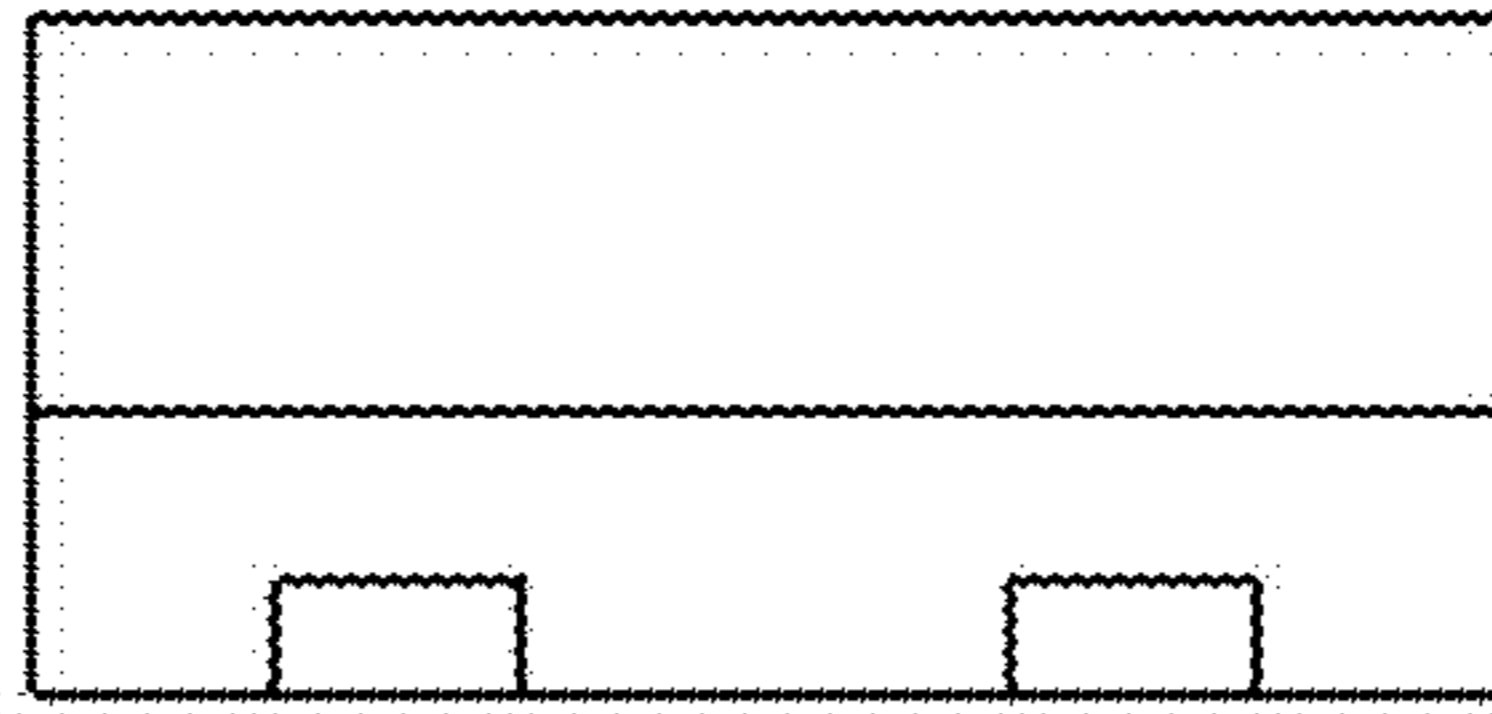


FIG. 12

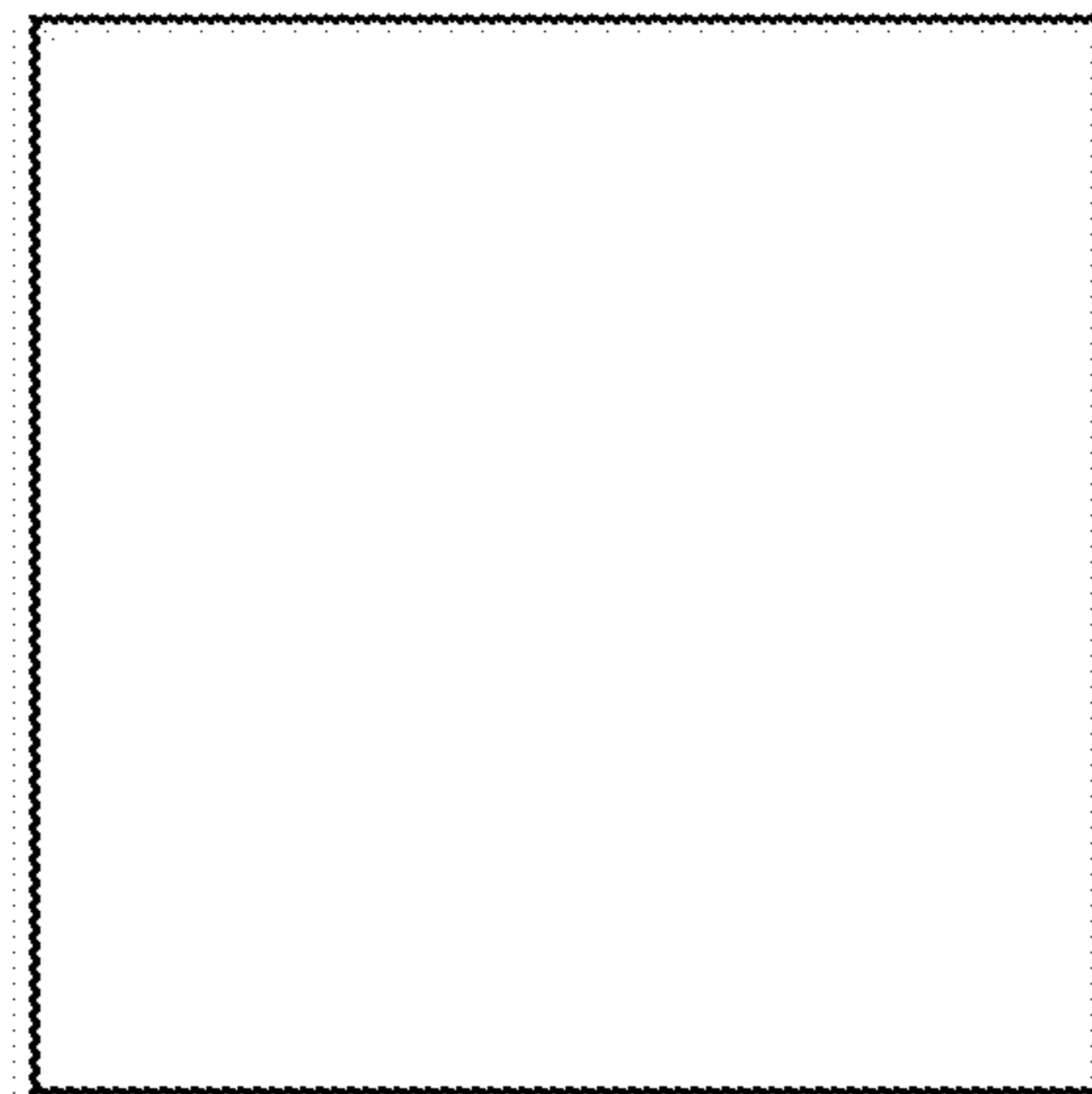


FIG. 13

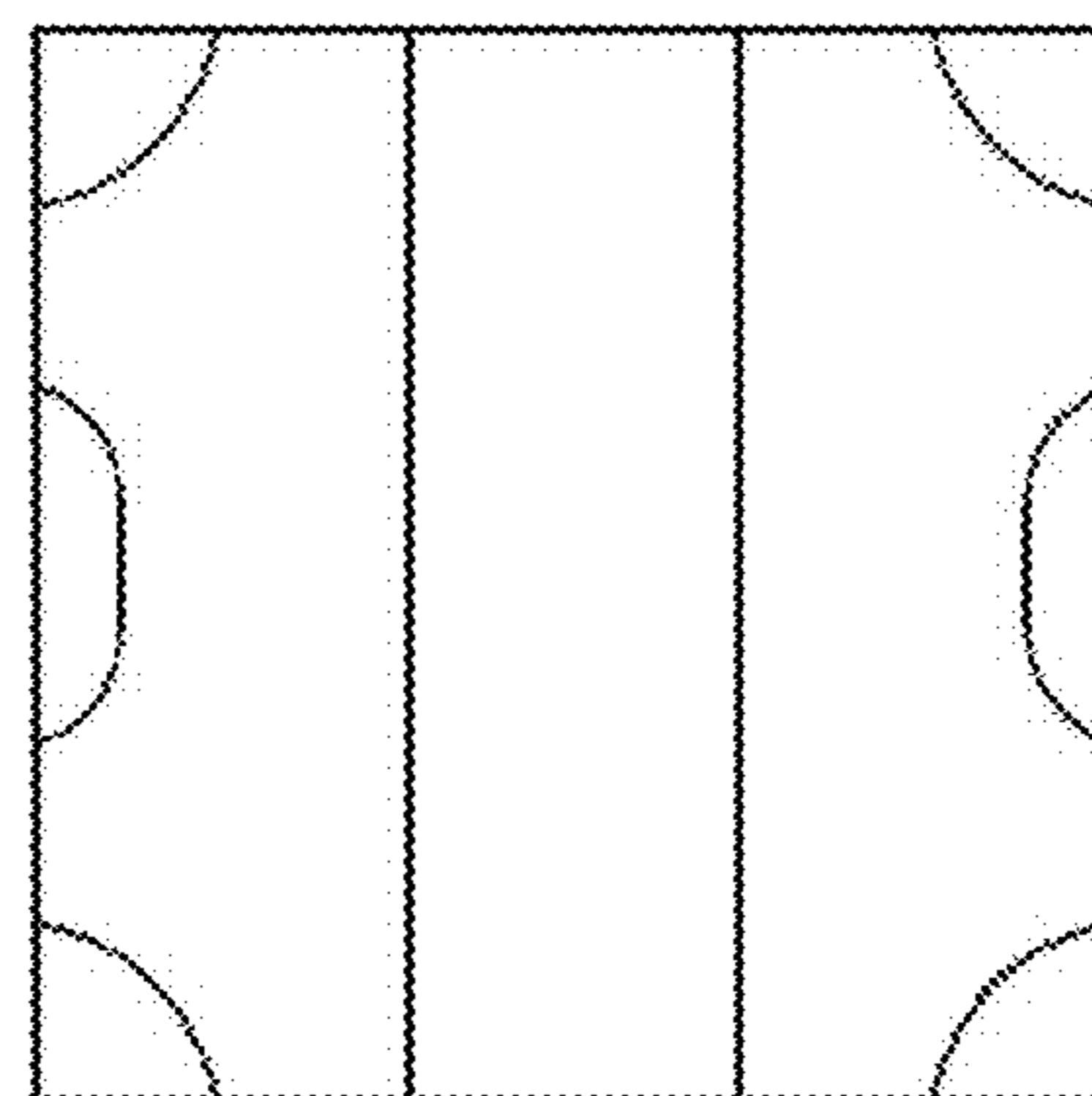


FIG. 14



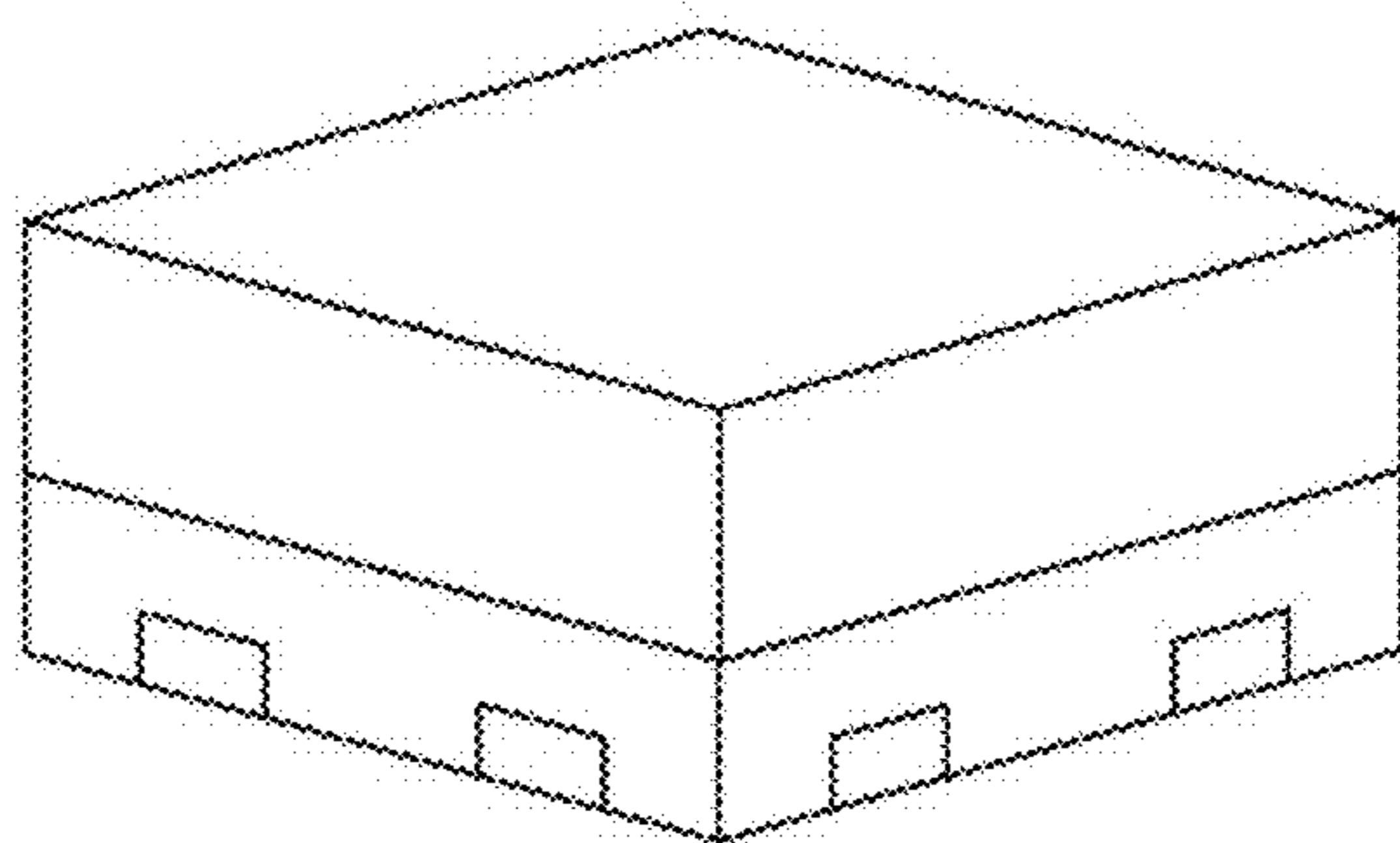


FIG. 15

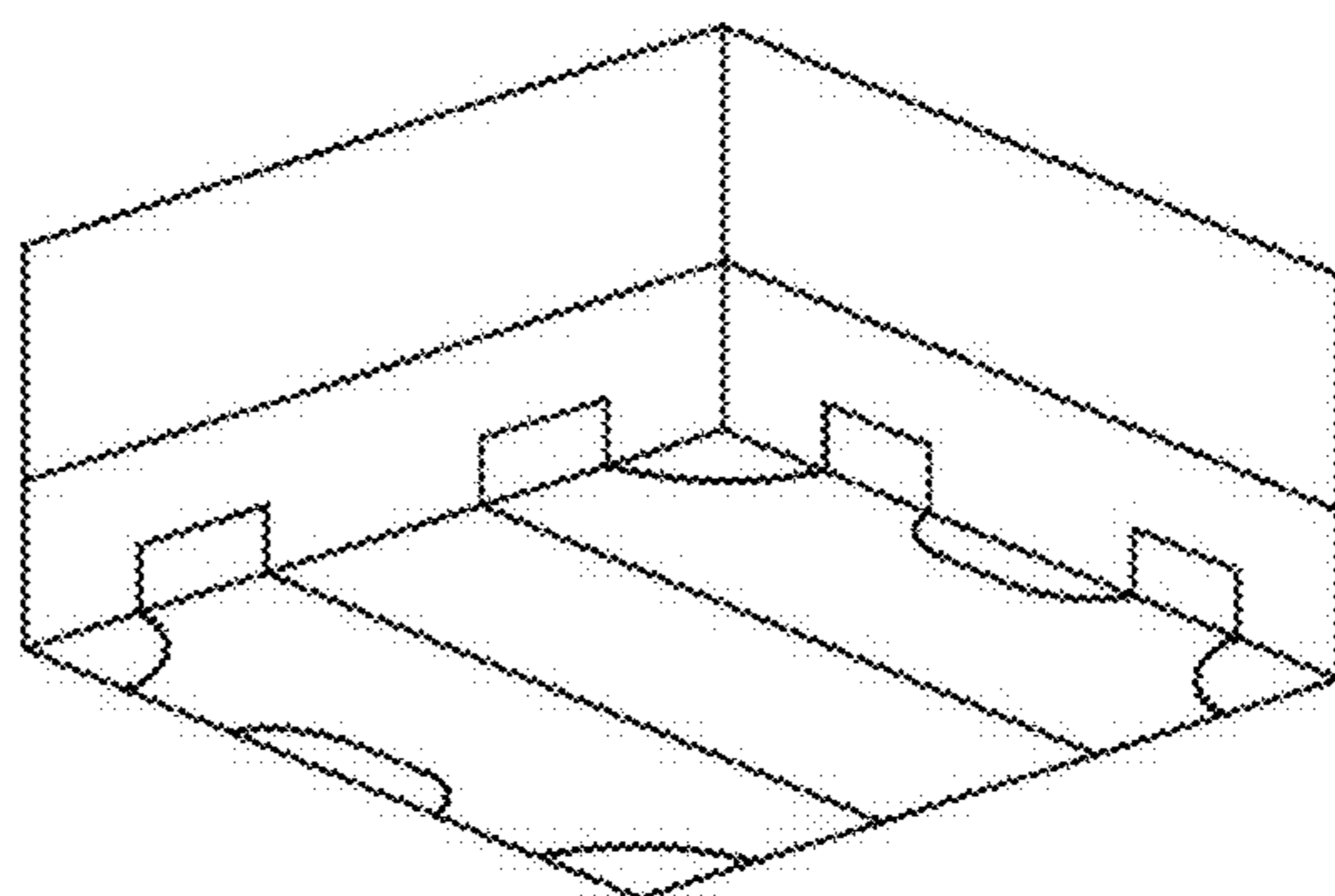


FIG. 16